

ABSTRACT

As a polishing composition which allows high-speed polishing while dishing and erosion are prevented and the flatness of metal film is maintained, there is provided a polishing composition for polishing a metal film provided on a substrate having trenches such that the metal film fills the trenches, so as to provide a planarized surface, wherein the composition comprises water, a phosphate ester having a C_{≥6} carbon atom alkyl group in its molecule, and an etchant for the metal, and has a pH of 5 to 11.